Performance Specification

Model	I_{hold}	Itrip	V_{max} Operating	V_{max} Interrupt	I_{max}	P_d	Maximum Time To Trip		Resistance		
							Current	Time	$Ri_{min.}$	$Ri_{max.}$	$R1_{max}$
	(A)	(A)	(Vdc)	(Vrms)	(A)	Typ. (W)	(A)	(Sec)	(Ω)	(Ω)	(Ω)
JK600-150	0.150	0.300	60	600	3.0	1.00	1.00	5.00	6.00	12.00	22.00
JK600-160	0.160	0.320	60	600	3.0	1.00	1.00	7.00	4.00	10.00	18.00

V max = Maximum operating voltage device can withstand without damage at rated current (Imax).

I max = Maximum fault current device can withstand without damage at rated voltage (Vmax).

I hold = Hold Current. Maximum current device will not trip in 25°C still air.

I trip = Trip Current. Minimum current at which the device will always trip in 25°C still air.

Pd = Power dissipation when device is in the tripped state in 25°C still air environment at rated voltage.

Ri min/max = Minimum/Maximum device resistance prior to tripping at25°C.

R1max = Maximum device resistance is measured one hour post reflow.

CAUTION : Operation beyond the specified ratings may result in damage and possible arcing and flame.

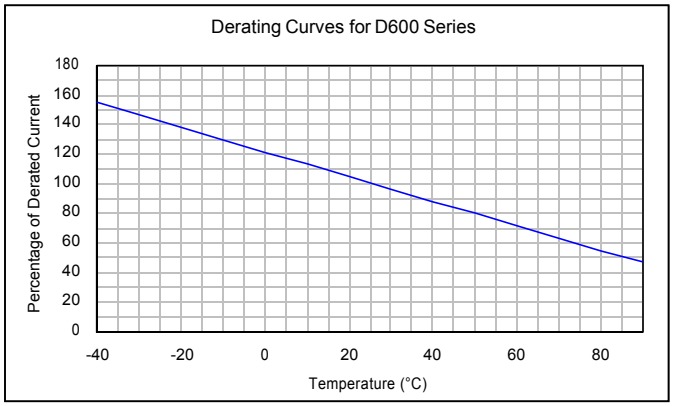
Environmental Specifications

Test	Conditions	Resistance change
Passive aging	+85°C, 1000 hrs.	±5% typical
Humidity aging	+85°C, 85% R.H. , 168 hours	±5% typical
Thermal shock	+85°C to -40°C, 20 times	±33% typical
Resistance to solvent	MIL-STD-202,Method 215	No change
Vibration	MIL-STD-202,Method 201	No change
Ambient operating conditions : - 40 °C to +85 °C		
Maximum surface temperature of the device in the tripped state is 125 °C		

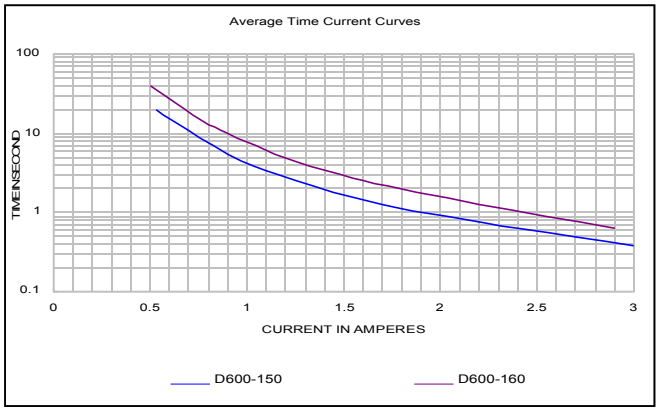
Agency Approval and Environmental Complianc

Agency	File Number	Regulation	Standard
UL	pending	Pb RoHS	2002/95/EC
TUV	pending	HF	EN14582

Thermal Derating Curve



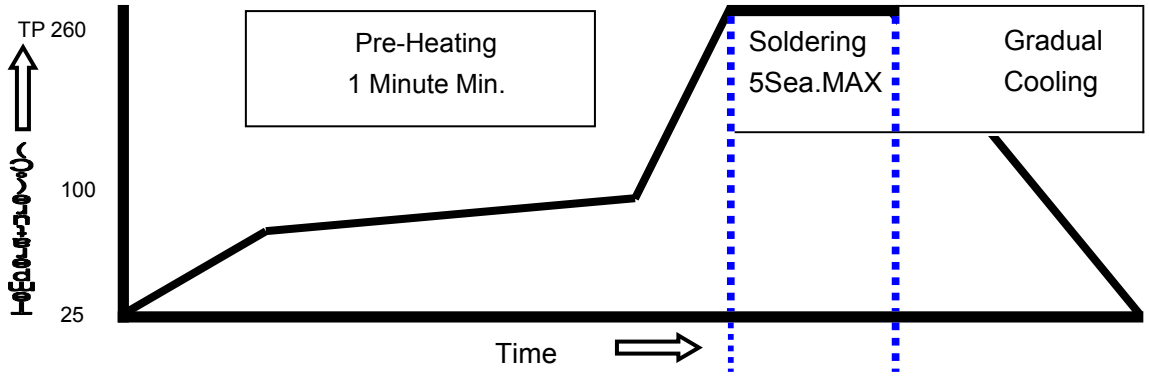
Average Time-Current Curve



Ihold Versus Temperature

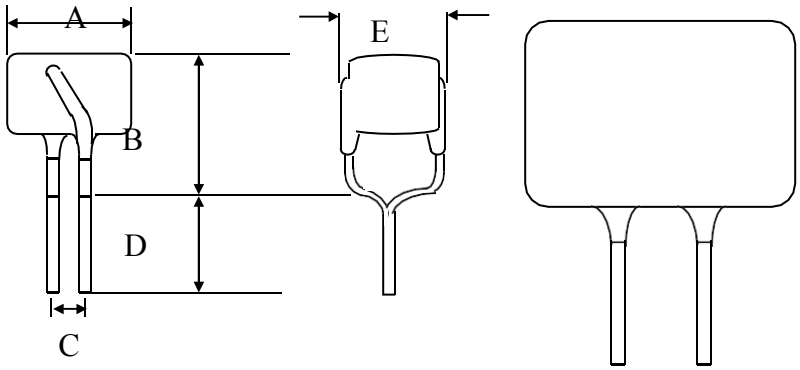
Model	Maximum ambient operating temperature (T_{mao}) vs. hold current (I_{hold})								
	-40°C	-20°C	0°C	25°C	40°C	50°C	60°C	70°C	85°C
JK600-150	0.233	0.206	0.178	0.150	0.124	0.110	0.096	0.083	0.062
JK600-160	0.249	0.219	0.190	0.160	0.132	0.117	0.103	0.088	0.066

Soldering Parameters



WAVE SOLDERING INFORMATIONS	
Pre-Heating Zone	Max. ramping rate should not exceed 4℃/Sec.
Soldering Zone	Max. solder temperature should not exceed 260℃
Cooling Zone	Cooling by natural convection in air.
◎ Specifications are subject to change without notice.	

Physical Dimensions(mm.)



Model	A	B	C	D	E	Lead
	Max.	Max.	Typ.	Min.	Max.	Style
JK600-150	13.5	12.6	5.1	4.7	6.0	Kink
JK600-160	13.5	12.6	5.1	4.7	6.0	Kink

PHYSICAL SPECIFICATIONS :

Materials :

JK600-: Tin-plated copper, 22AWG, Φ0.65mm(0.026 in).

Lead Solderability : MIL-STD-202, Method 208E

Packaging Quantity

JK600-	150	RA	B-0.5	Reel Q'ty		Bag Q'ty	
Product	Hold	Rx=	B-x.x=	600		500	
Series	Current	Resistance	Resistance bin range				
	(mA)	range	within 0.5 ohms				
		(Optional)	in one lot(Optional)				

Tape & Reel packaging per EIA468-B standard.